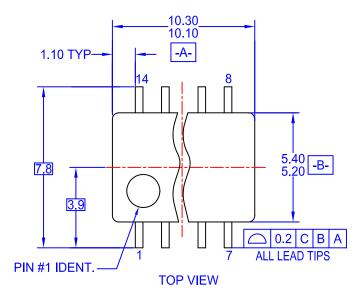
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

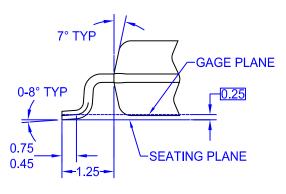
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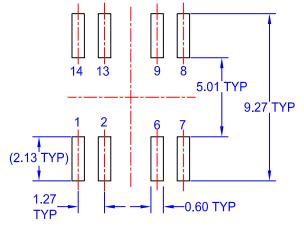


DUSEU

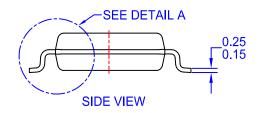
ALL LEAD TIPS 2.1 MAX -C-1.27 TYP -C-0.16 0.16 0.14 0.16 0.14 0.12 (M) C A



DETAIL A



LAND PATTERN RECOMMENDATION



NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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